DS92LV18,SCAN921821



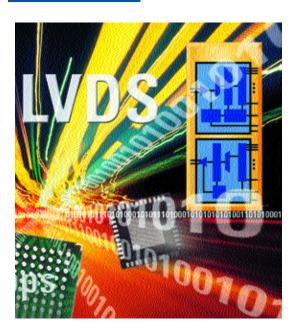
Literature Number: SNLA202

National Semiconductor 18-bit SerDes Design Guide



Serializing Made Simple

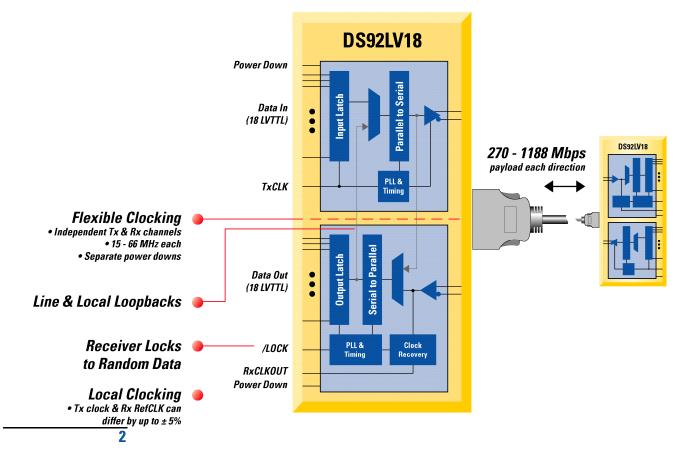
Introduction



The DS92LV18 and SCAN921821 are members of National's robust and easyto-use Bus LVDS serializer/deserializer (SerDes) family already popular in a wide variety of telecom, datacom, industrial, and commercial backplane/cable interconnect applications. They are similar to the original 10- and 16- bit Bus LVDS SerDes products, but provide a wider, 18-bit data bus payload to support not only byte-oriented data but also carry other information such as parity, frame, control, status, sync, low frequency bus or clock signals, etc.

The DS92LV18 and SCAN921821 are very flexible and performs over a wide, 15 - 66 MHz frequency range. Both the transmit clock and receiver reference clock have high jitter tolerance, allowing the use of low cost clock sources. The DS92LV18 serializer and deserializer sections are fully independent and can be operated at different frequencies. This is useful when upstream and downstream rates are not balanced. The SCAN921821 is a dual transmitter that features programmable pre-emphasis to drive long cables .

The DS92LV18 receiver locks to random data, eliminating the need to interrupt normal traffic with PLL training patterns after hot plug events. The usual loss-of-lock feedback path from receiver to transmitter is also not required. Line and local loopback test modes allow the designer to segregate portions of the system to facilitate system diagnostics.



Bus LVDS SerDes Architecture

The Bus LVDS SerDes architecture was developed in conjunction with major telecommunications customers who desired features not provided by common 8b/10b datacom SerDes chipsets. Instead of scrambling each byte into a new 10-bit code as with 8b/10b coding, the Bus LVDS SerDes coding scheme frames each data word with two embedded clock bits, one high and one

1 2 3 4 5 6 7 8 9 10 8b/10b Coding Scheme: Two 10-bit Codes Cik1 DIN1 DIN2 DIN4 DIN5 DIN6 DIN7 DIN8 DIN9 DIN19 DIN13 DIN14 DIN15 DIN16 Cik0 DS92LV16 Coding Scheme: 16 bits plus Embedded Clock Bits Distance Distan

Coding efficiency comparison between a 16-bit Bus LVDS and a16-bit 8b/10 SerDes.

ATA

Periodic

Embedded Clock Transition

low. These embedded clock bits create a rising edge transition which provides precise timing and framing information to the receiver on every clock cycle.

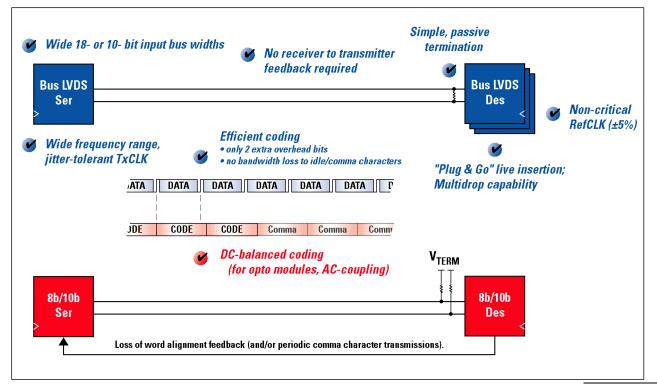
The resulting benefits of the Bus LVDS SerDes architecture include:

■ Lock to random data for true hot plug capability—lock can be achieved *without* interrupting traffic with PLL training patterns and *without* a loss-of-lock feedback path from receiver to transmitter.

■ The relaxed ±5% RefCLK frequency specification means the receiver does *not* require a precise reference clock source to recover data reliably.

■ Jitter-tolerant TCLK transmit clock input eliminates the requirement to use a high-grade telecom/datacom transmit clock source and also simplifies external loopback operations.

■ Non-byte-oriented bus widths such as 18- and 10-bits are available.



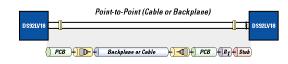
DAT/

Bus Topologies/Applications

The DS92LV18 is designed mainly for point-to-point applications, but you may also use it for multidrop interconnects under certain circumstances. The SCAN921821 should be used only for point-to-point applications.

Point-to-Point

The DS92LV18 and SCAN921821 can deliver the full 1.188 Gbps payload over point-to-point backplanes and cables (distance depends on cable quality, transmission speed, etc.) This performance is also possible when driving multiple receivers through a low jitter LVDS-to-LVDS switch/distribution chip in a distributed point-to-point configuration. In all point-to-point applications, you must place a termination resistor close to each receiver input.



Distributed Point-to-Point (Cables or Backplane)

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Switch or Splitte CAN90CP02, DS90CP0 DS90LV110, otc

Multidrop

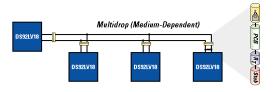
The DS92LV18 may be used in limited multidrop (also known as point-to-multipoint) backplane applications driving a few receiver loads. The output structure is a modified Bus LVDS-type circuit that regulates the V_{OD} (output differential voltage) over a narrow range of loads. The driver expects to see a 100-Ohm load, but may also operate with loads as low as 50 Ohms with reduced voltage swing. The number of receivers allowed depends upon the bandwidth of the interconnecting path, the spacing of the nodes, and also the length of the resulting stubs. The DS92LV18's fast Bus LVDS output edge rates are optimized for the high throughput of the part, thus stub length must be minimized mechanically or electrically using "stub hider" buffer devices.

See the "Backplane" section for more information.

	Typical Bus Pe	Termanoo	
Backplane Topology	Configuration	Performance	D\$92LV16
Point-to-Point	1 Tx 🖛 1 Rx	Chipset Maximum	Recommended 🔵
Distributed Point-to-Point	1 Tx ➡ Switch ➡ Multiple_Rx's	Chipset Maximum	Recommended 🔵
Limited Multidrop	1 Tx ➡ 2-4 Rx	Up to 500 - 660 Mbps	Limited Applications 🔘
Multidrop	1 Tx 🕶 10-20 Rx	Up to 300 - 400 Mbps	NOT Recommended 🔴
Multipoint	10-20 Transceivers	Up to 200 - 300 Mbps	NOT Recommended 🔵

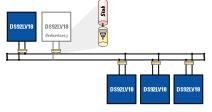


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Multidrop Driving from End Slot(s) (Medium-Dependent)



Match segment Z₀'s & R_T impedances within \pm 10% (10% missmatch \approx 5% reflection) Z₀ = <u>Beckplane or Cable</u> = <u>PCB</u> = <u>Stub</u> = <u>(</u>R_T)

Minimize stub lengths

Use appropriate connector pin assignment & routing

Backplanes

Point-to-Point

The DS92LV18 and SCAN921821 achieve the maximum 1.188 Gbps performance in controlled 100-Ohm differential impedance point-to-point or distributed point-to-point FR-4 backplanes, though other backplane materials such as GETEK, Rogers, or hybrids may also be employed if desired. Closely-coupled differential backplane traces should be employed, though differential connectors are not strictly required (e.g. 2mm HM connectors are often used).

Multidrop

In some instances, the DS92LV18 may be used in multidrop backplanes driving 2 - 4 receiver loads. Actual performance depends on the bandwidth of the interconnect. Pay close attention on minimizing stub lengths (connector plus trace) to < 2 cm. Depending on data rate, National's LVDS DS90LV001 or DS92001 "stub hider" chips can be used to reduce stub lengths seen by the signal on the backplane. Receiver loads should be widely spaced to reduce the transmission segment to stub length ratio and/or placed far away from the transmitter to allow the edge rate to be slowed by the interconnect before reaching the first stub.

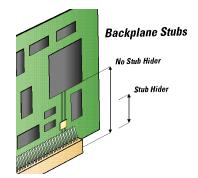
Due to fast edge rates, the DS92LV18 is typically not recommended for driving more than a few multidrop loads.

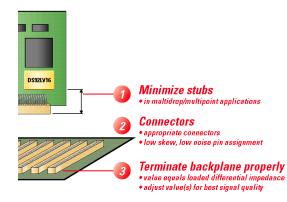
Termination

Termination is required. Choose the termination resistor value R_L to match the loaded differential impedance of the transmission line. In a point-to-point backplane, the termination value is typically 100 Ohms. If a smaller output signal swing is desired, the line may be terminated at both the transmitter output as well as the receiver input, reducing the effective load seen by the transmitter by half.

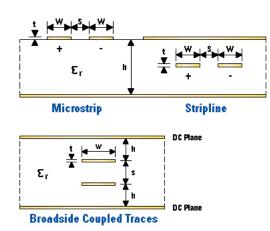
In a multidrop backplane, the added capacitive loading of the extra receivers lowers the differential impedance, requiring a lower value termination resistor. Again, the termination resistor(s) value chosen should match the loaded backplane impedance. Note that loads less than 50 Ohms reduce the output signal swing below \pm 350 mV, compromising noise margins.

The typical capacitance of the DS92LV18 and SCAN921821 serial Bus LVDS inputs and outputs is about 5 pF.

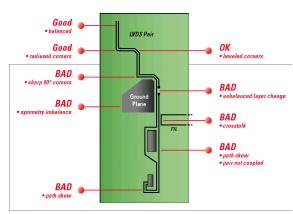




PCB Recommendations



Minimize "s" and adjust "W" for proper differential impedance.



The LVDS pair should be treated as "one signal." Avoid unbalancing influences and keep TTL lines away from the LVDS pair.

! Tip

Designing with LVDS is actually quite easy if you remember that LVDS is a *high speed, differential* signaling technology.

High Speed: LVDS pairs should be considered transmission lines. Anything over a few centimeters should have controlled impedance. LVDS termination is always required.

Differential: Each LVDS pair should be treated as one signal. Both wires of each pair should "see" the same electrical path.

General Printed Circuit Board (PCB) Recommendations

■ Use at least 4 PCB board layers (Bus LVDS signals, ground, power, and TTL signals).

Minimize any resulting stub lengths—

In a point-to-point bus, the resulting stub is typically the distance between the termination resistor and the receiver input pins of the DS92LV18. Place the small surface mount resistor as close to the receiver input pins as possible.

In a limited multidrop bus, the termination is typically at the far end of the bus only. The resulting stubs are from the main line to the receiver inputs and these distances should be minimized.

■ Segment impedance matching – in a backplane point-to-point bus, the location of the serializer and deserializer is less critical. More important is matching the impedance of all transmission line segments. These impedances should be matched within 10% of the nominal value.

■ Controlled impedance differential traces of 100 Ohms are typically recommended for Bus LVDS signals. Edge-coupled microstrip, edge-coupled stripline, or broadside-coupled stripline differential traces may be used. These traces should be closely-coupled (i.e. "s" should be minimized) to ensure coupled noise will appear as common-mode (which is rejected by the receiver). This has the added benefit that closely-coupled lines that are excited with odd-mode transmission tend to radiate less electromagnetic energy.

■ Treat the LVDS pair as one signal, avoiding influences that cause imbalances within the pair (see diagram at left). Minimize skew within the pair. Maintain "balance."

■ Leave unused Bus LVDS receiver inputs open (floating) – the internal failsafe in the DS92LV18 will pull the input to a valid state.

■ Termination of the Bus LVDS signals is required. The termination resistor value should match the differential impedance of the transmission line. 100-Ohm is a typical value for point-to-point applications. It is better to err with too large a termination resistor than too small.

■ Isolate TTL/CMOS signals from Bus LVDS signals, placing them at least "3s" or "2w" away—whichever is larger. This will help to prevent them from coupling onto the LVDS lines.

These are just a few common practices that should be followed when designing PCBs for LVDS signaling. General application guidelines are available in the LVDS Owner's Manual and other documents at lvds.national.com.

Cables & Connectors

Cables

The DS92LV18 and SCAN921821 can be used over a wide variety of balanced cables depending on distance and signal quality requirements. In general, twinax or twisted pair cables are recommended.

■ Typical Connections can be made using category 5 (CAT5) twisted pair ethernet cable with RJ-45 connectors. See graph at right for typical data rate versus cable distance.

■ Higher Speed Links: AMP Z-PACK®, Belden 89207 twinax, or other twinax cables can be used.

■ Higher Pincount: SCSI-type cables and connectors or LVDS-type cable assemblies such as the 3M[™] MDR and Amphenol SKEWCLEAR® systems are commonly used.

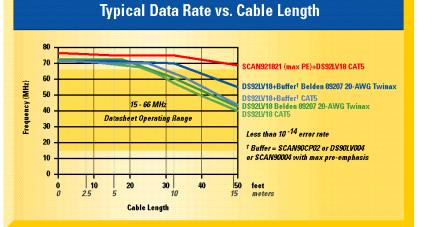
■ Very Short Distances (< 0.3 m): flex circuit (following correct PCB layout) or unbalanced ribbon cable may even be used.

If running multiple Bus LVDS pairs in the same cable assembly, use individually shielded pairs to minimize crosstalk between the pairs. At least one ground conductor should be used in the cable (connecting to the DS92LV18 analog grounds (AGNDs)) to provide a known, low impedance return path for common mode currents.

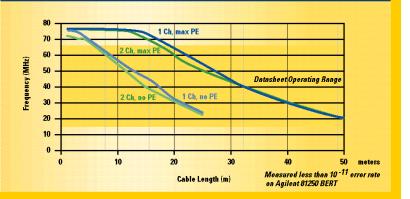
A termination resistor R_L , placed as close as possible to the receiver inputs in point-to-point applications, is required. The resistor value should be chosen to match the differential impedance of the cable.

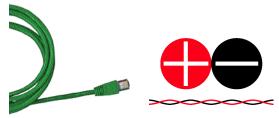
Connectors

Connectors with differential conductors offer the highest performance, but are not necessary in typical, lower speed or short distance applications. For single-ended connectors, keep LVDS pins away from other signals, particularly TTL/CMOS/LVTTL/LVCMOS signals. The "+" and "-" signals of a pair should be routed on the same row in multi-row connectors to help minimize skew. For high-speed applications (> 800 Mbps) using differential-optimized connectors is recommended.

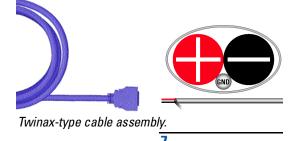


SCAN92821 -> DS92LV18 Over 0 - 50 m CAT5e Cable





CAT5 ethernet cable with RJ-45 connectors.



General Recommendations

A solid power/ground system is the foundation on which a reliable interconnect system is built. Design circuit board layout and stackup for the system to provide noise-free power to the device. Good layout practice will separate high frequency and high level inputs and outputs to minimize unwanted stray noise pickup, feedback, and interference. Power system performance may be greatly improved by using thin dielectrics (4 to 10 mils) for power/ground sandwiches. This increases the intrinsic capacitance of the PCB power system, which improves power supply filtering—especially at high frequencies—making the value and placement of external bypass capacitors less critical. External bypass capacitors should include both RF ceramic and tantalum electrolytic types. Use RF capacitors in the range of 0.001 μ F to 0.1 μ F. Use tantalum capacitors in the range of 2.2 μ F to 10 μ F. The voltage rating of tantalum capacitors should be at least 3 (5 preferred) times the power supply voltage being used.

It is recommended practice to use two vias at each power/ground pin as well as all RF bypass capacitor terminals. Dual vias reduce the interconnect inductance by up to half, thereby extending the effective range of bypass components. Locate RF capacitors as close as possible to the supply pins and use wide, low impedance traces—not 50-Ohm traces. Surface mount capacitors are recommended due to lower parasitics. When using multiple capacitors per supply pin, locate the smallest value closest to the supply pin. A bulk capacitor is recommended at the point of power entry. This is typically in the range of 50 µF to 100 µF and will smooth low frequency noise.

Some devices have separate power/ground pins for different portions of the circuits to isolate switching noise effects between different blocks. Connecting these to separate power/ground planes on the PCB is typically not required. Pin description tables typically describe which blocks are connected to which power/ground pins. In some cases, an external filter may be used to provide clean power to sensitive circuits such as PLLs.

Specific Recommendations

General device-specific bypassing recommendations are given below. Actual best practice depends on other board and system level criteria including board density, power rail and power supply type, and the supply needs of other integrated circuits on the board.

PVDD/PGND PLL Supply

The PVDD pins (the DS92LV18 has 2 PVDD pins) supply the PLL circuits. PLLs require a clean supply—less than 100 mV noise peak-topeak—for the minimization of jitter. PVDD noise in the frequency range 200 kHZ to 5 MHz can increase jitter and reduce noise margins. Certain power supplies may have switching frequencies or high harmonic content in this range. If this is the case, filtering of this noise spectrum may be required. A notch filter response is best to provide stable VDD, suppression of the noise band, and good high frequency response (clock fundamental). This may be accomplished with a CRC or CLC pie filter. If employed, a separate pie filter is recommended for each PLL to minimize the voltage drop due to series resistance. Separate board power planes for each PVDD are typically not required.

AVDD/AGND LVDS Supply

The AVDD pins (the DS92LV18 has 4 AVDD pins) supply the LVDS ciruits. Due to the nature of the DS92LV18 and SCAN921821 designs, large currents are not drawn through these pins and a 0.1 μ F capacitor is sufficient for these pins. If space is available, a 0.01 μ F capacitor may be used in parallel with the 0.1 μ F capacitor for additional high frequency filtering. Connect the AGND ground to the cable

Power & Ground (continued)

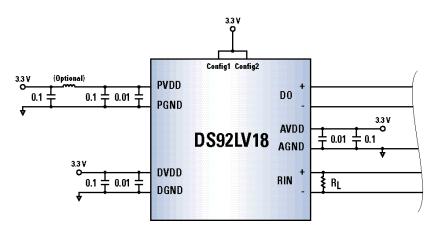
ground to provide a return path for any common (even) mode currents. Most of the LVDS current is odd-mode and returns within the pair, though a small amount of odd-mode current may be present due to coupled noise and the cable ground should return through a low impedance path to AGND.

DVDD/DGND Digital Supply

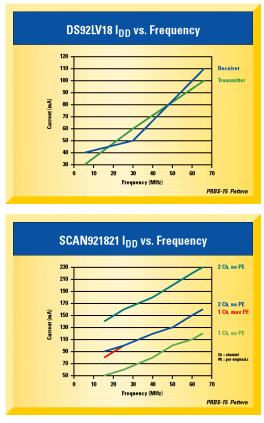
The DVDD pins supply the digital portion of the device and also the DS92LV18 receiver output drivers. The DS92LV18 DVDD is more critical than SCAN921821 DVDD pins because the DS92LV18 DVDD pins must power the receiver outputs during multiple output switching conditions. Four DS92LV18 receiver outputs are powered by each DVDD pin, suggesting that a minimum local bypass capacitance of 28 nF is required. This is calculated by taking 4 times the maximum short circuit current (4 x 85 mA = 340 mA), multiplying by the output rise time (4 ns), and then dividing by the maximum allowed VDD droop (assume 50 mV) and yields 27.2 nF. Rounding up, a standard 0.1 μ F is selected for each DS92LV18 DVDD pin.

Power Up Sequencing

The DS92LV18 and SCAN921821 do not require a specific power up sequence. Best practice is: power up all VDD pins together, apply clocks (RefCLK & TCLK), and then bring /PWDN powerdown pins high to enable the transmit and/or receive channels. The chip has a power-on reset (POR) circuitry which holds the outputs in TRI-STATE until the supply is above approximately 2.5V. Since all VDD pins (PVDD, AVDD, & DVDD) are related internally, they must be powered up and down together.



Typical connection diagram showing power supply bypassing. Employ sufficient bypassing to ensure < 100 mV peak-to-peak noise on supply pins, especially PVDD. Each DVDD pin should have separate bypass capacitance.



Typical total I_{DD} versus frequency. (3.3 V, 25° C)

! Tip

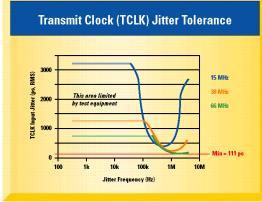
Comparing Power Consumption

There is no industry-standard method for specifying power consumption in SerDes datasheets. Power consumption varies significantly with output load, pattern, clock frequency, and the number of channels tested. Even so-called "worst-case" power consumption conditions vary greatly from vendor to vendor. For instance, many vendors do not include the receiver parallel output bus load current.

The DS92LV18 maximum datasheet power consumption is specified at worst case voltage (3.6 V), temperature, and pattern (checkerboard, i.e. alternating LVTTL ones and zeros) with 15 pF load on all CMOS outputs and both transmit & receive channels running at maximum clock frequency (66 MHz).

Clocking







Maximum RMS TCLK input jitter tolerance versus jitter frequency under typical conditions.

! Tip

Clock Jitter

The transmitter will pass a certain amount of jitter contained on the TCLK clock to the serial data. This can affect noise margins. Similarly, some of the jitter on the clock 0,1 rising edge will be passed by the receiver to the RCLK output.

Although the 18-bit SerDes are very tolerant to jitter, minimizing cycle-to-cycle jitter in the range of 200 kHz - 2 MHz on both TCLK and the PLL supplies will maximize noise margins.

Transmit Clock (TCLK)

The transmit clock (TCLK) rising edge is used by the transmit block to latch in the DIN[0:17] parallel bus and run the transmitter's PLL. The TCLK input is LVTTL/LVCMOS compatible.

The TCLK clock input tolerates jitter of **80 ps RMS** allowing the use of nontelecom/datacom-grade clock sources. The receiver output clock RCLK can also be fed back to TCLK and data retransmitted as an external loopback or repeater, though only two "hops" total are recommended before filtering out accumulated clock jitter. Excessive jitter, especially in the range of 200 kHz - 2 MHz, can appear on the serial outputs reducing link noise margins.

Be careful not to confuse RMS and peak-to-peak jitter. Peak-to-peak jitter tolerance will be higher (actual value depends on desired bit error rate (BER)).

If TCLK is interrupted, the chipset will go through the resynchronization procedure upon reapplication of valid TCLK.

Receiver Reference Clock (RefCLK)

The receiver reference clock is an LVTTL/LVCMOS compatible input and is used by the receiver to establish receiver PLL lock and prevent locking to a false harmonic. Therefore, the RefCLK characteristics are not very critical and the RefCLK frequency need only be within $\pm 5\%$ of the TCLK frequency of the transmitter from which the chip is receiving data. Unless a loopback test is being performed, this RefCLK frequency need not be the same frequency as the chip's own TCLK signal since the transmit and receive blocks are fully independent, i.e. upstream and downstream data rates are independent.

The relaxed RefCLK specs mean that the RefCLK signal can be generated locally using a common, low cost clock source. In fact, the RefCLK signal could even be removed once the receiver is locked (though this is not recommended).

Receiver Output Clock (RCLK)

The receiver output clock is an LVCMOS output whose rising edge is aligned to the middle of the receiver output data ROUT[0:17]. The subsequent ASIC/FPGA device should latch in ROUT[0:17] data meeting the ASIC's/FPGA's input setup and hold times. Output jitter for RCLK is not specified on the datasheet since it depends on the jitter of the incoming data and the TCLK clock source.

Inputs & Outputs

Unused LVTTL Inputs

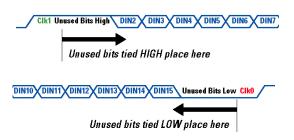
Unused LVTTL inputs may be left floating or tied high or low. The device datasheet indicates the presence of pull down devices to bias unused pins. These internal impedances tend to be in the 200 kOhm range and may be overridden with lower value pull up resistors if desired. If not using the full 18 bits of the payload, careful attention needs to be taken to avoid disrupting the random lock feature. These unused bits will still be transmitted, so in order for the receiver to maintain random data lock capability, care must be taken not to create a situation where the unused bits cause a repetitive multiple low-high transitions (RMTs). Avoid this by tying bits high at the LSB inputs (starting with DIN0) and bits tied low at the MSB inputs (inputs ending with DIN17).

Floating Bus LVDS Receiver Inputs & Failsafe

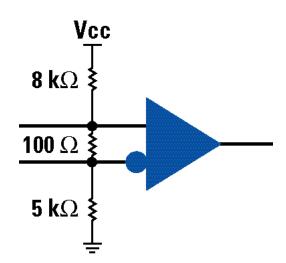
In the event that the DS92LV18 receiver is disconnected from the backplane/cable, the internal failsafe circuitry is designed to reject a certain amount of differential noise (about 10mV) from being interpreted as data or clock. This seems like a very small threshold, but balanced, closely-coupled LVDS lines tend to pick up noise as common mode—not differential. The CMOS ROUT[0:17] outputs of the DS92LV18 deserializer will be TRI-STATE when the incoming serial data is removed and the receiver loses lock. Additional failsafe biasing can be implemented externally (see application note AN-1194 and *LVDS Owner's Manual* sections 4.6.2-3) at the expense of two additional resistors.

Receiver CMOS Output Drive

The receiver CMOS outputs are specified at 9 mA. This is typically sufficient to drive 2-3 LVTTL/LVCMOS loads. If more loads will be driven, especially at higher clock speeds, a logic buffer is recommended. Note that depending on actual configuration (number of loads, stub lengths, segment distances, etc.), the receiver output bus may need to be treated as a transmission line and proper LVTTL/LVCMOS termination techniques employed.



Example showing two unused bits pulled high and two unused bits pulled low to avoid RMTs.



An example of external faisafe biasing for the DS92LV18. See application note AN-1194 and LVDS Owner's Manual sections 4.6.2-3 for details.

Evaluating the DS92LV18



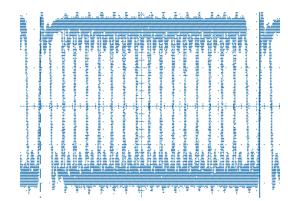
LVDS-18B-EVK evaluation kit

Evaluation Board

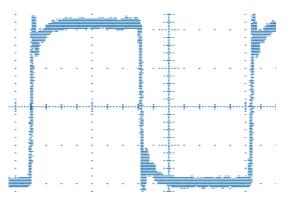
The DS92LV18 and SCAN921821 evaluation kit provides the ability to evaluate the chips over any user-supplied interconnect via its SMA connectors or over CAT5/6/7 cables using the SMA-to-RJ45 adapters (included). This eval kit can be ordered from authorized distributors as part number LVDS-18B-EVK subject to availability. This evaluation kit contains two DS92LV18 devices and one SCAN921821 device on the printed circuit board.

Probing Bus LVDS Signals

LVDS signals are high speed, low swing signals. Improper probing can result in deceiving results since the probe and/or scope can filter high speed coponents of the signal. Using a \geq 1 GHz bandwidth scope (such as the Agilent 86100 or Tektronix 694C) and a high speed differential probe (such as the Tektronix P6247/8 or P6330) is highly recommended. LVDS drivers are not compatible with 50-Ohm probes.



PRBS pattern at serializer output . Note the embedded low/high clock 0/1 bits. (DS92LV16 waveform shown.)



SYNC pattern at serializer output.



Tektronix 1GHz P6247 differential probe. Note two probe contacts and polarity indication in probe tip detail.

Loopback Testing

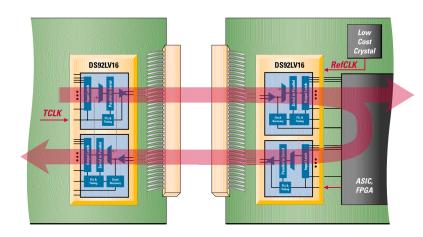
The line and local loopback modes allow the designer to isolate and test selected portions of the system.

Local Loopback

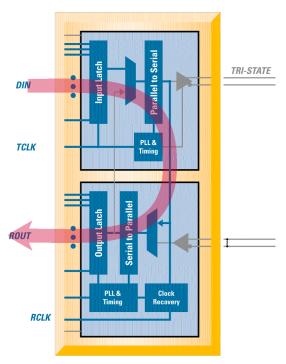
Asserting the LOCAL_LE pin high connects the parallel LVTTL data bus DIN[0:17] internally to the receiver output ROUT[0:17]. This mode includes all the functional blocks of the SerDes pair except the Bus LVDS input and output structures (the transmitter Bus LVDS outputs are in TRI-STATE). Switching the DS92LV18 to local loopback mode, therefore, means the receiver will relock to the loopback data and RefCLK must be within ± 5 % of the local TCLK frequency. The local loopback mode allows the local card to verify it is sending, receiving, and processing data properly.

Line Loopback

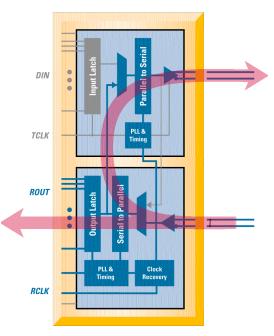
The DS92LV18 will enter the line loopback mode when the LINE_LE pin is brought high. This connects the Bus LVDS transmitter output (DO) pins internally to the receiver input (RIN) pins and to the parallel LVTTL data bus ROUT[0:17]. This loopback test mode includes the serializer/deserializer blocks. The line loopback mode allows the system to verify that the board-to-board links are operating properly.



Due to the relaxed clocking requirements of the DS92LV18 and SCAN921821, external line loopback within an FPGA or ASIC can also easily be performed to test portions of the system logic in addition to the DS92LV18 and interconnect.



Local loopback mode.

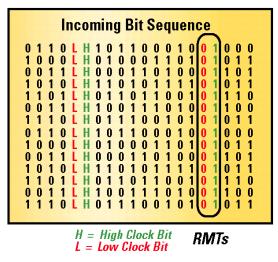


Line loopback mode.

Lock to Random Data vs. SYNC Patterns

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U	1	1	U	Ŀ	н	1	U	1	1	U	U	U	1	U	1	1	U	U	0
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1	0	1	0	L	Н	1	1	0	1	0	1	1	1	1	0	1	0	1	1
1	1	0	1	L	Н	0	1	1	0	1	1	0	0	1	1	0	1	1	0
0	0	1	1	L	Н	1	0	0	1	1	1	0	1	0	0	1	1	0	0
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- 83					191919	alala		0.0.0											

Incoming data stream (arranged in 18-bit words) showing no RMT's. Receiver will aqcuire lock.



Incoming data stream with RMT's. RMT's must disappear before the receiver can acquire lock.

SYNC Patterns

SYNC patterns, "H11111111000000000L" where "H" is the clock 1 bit (high) and "L" is the clock 0 bit (low), are sent automatically by the transmitter when the SYNC pin is held high. The receiver will lock to this pattern within a guaranteed time (see t_{DSR} specified in the datasheet). When the deserializer's /LOCK pin goes LOW, the receiver has locked to the incoming data stream and valid data appears at the receiver outputs.

Lock to Random Data

The receiver will also lock to random data without external system intervention, providing a powerful "plug & go" system capability not provided by most SerDes chipsets. In order to achieve this, the receiver looks for a consistent low-high transition caused by the clock 0,1 bits. If there are two data bits consistently "stuck" low-high over multiple clock cycles (known as a repetitive multiple transition or RMT), the receiver will not lock until these bits change and the receiver recognizes the unique embedded clock low-to-high transition.

Sending SYNC Patterns versus Lock to Random Data

Sending SYNC patterns has the advantage that the receiver lock time is guaranteed to be less than t_{DSR} max. This can be useful in some systems and the sending of SYNC patterns can be achieved by controlling the SYNC pin through system logic or by feeding back the /LOCK pin to the SYNC pin.

The receiver will lock to random data without system intervention, though the lock time will depend on the data pattern. This feature is useful in systems in which there is no quick or easy feedback path from receiver to transmitter or in systems which can't afford to interrupt data flow by sending special training patterns.

Both lock modes, sending SYNC patterns and the locking to random data, are viable synchronization methods. Either may be employed and in fact, some systems may choose to employ both methods.

Once Lock is Acheived

After the receiver is locked, it will stay locked regardless of data pattern: fixed (with or without RMTs), random, periodic, SYNC patterns, or a mix of these patterns. The receiver loses lock and enters the "acquire lock" state only after it detects two consecutive clock 0,1 bit errors. Once locked, the data between the clock bits do not affect the receiver's PLL.

Interconnect Jitter Budget

Interconnect Jitter Budget

Interconnect jitter budget is the amount of interconnect loading that can occur on the link before bit errors occur and is simply the ideal receiver noise margin t_{RNMI} specification. The latest DS92LV18 datasheets specify both left and right t_{RNMI} , indicating how much jitter the receiver can tolerate on either side of the ideal bit edge before bit errors occur. The t_{RNMI} specifications also allow the construction of an eye mask to validate the application's signal quality. Jitter sources include:

- External Noise: This includes excessive power supply noise, cross talk, etc.
- Interconnect Effects: Inter-symbol interference (ISI), attenuation, etc.
- Clock Jitter: excessive jitter on the serializer transmit clock TCLK.

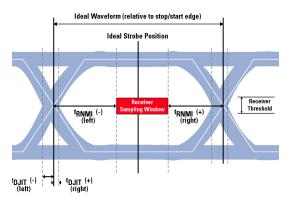
Validating Signal Quality

In conjunction with bit error rate test (BERT) measurements, eye pattern measurements are a good way to validate the robustness of a high speed link. While BER tests generally produce a pass/fail result, viewing the eye pattern at the receiver inputs gives a more qualitative indication of how much margin a given link has. The amount of "eye opening" around the receiver input jitter mask is a qualitative measure of the link's noise margin.

The receiver input jitter mask is constructed in the following steps:

1) Make sure the link is operating and sending the desired pattern (normally a PRBS pattern).

Ideal Bit Width (ns) at Common Frequencies							
MHz	ns	MHz	ns				
29.49	1.695	40	1.250				
30	1.667	50	1.000				
30.72	1.628	52	0.962				
33	1.515	58.98	0.848				
35	1.429	61.44	0.814				
38.8	1.289	62.5	0.800				
39.44	1.268	66	0.758				
lde	al Bit Width =	1/TCL <mark>K frequer</mark>	ncy/20				



This section of the design guide shows how to construct a receiver input jitter mask. This eye pattern is computer-generated for clarity.

! Tip

The serial eye pattern should be measured using a high bandwidth, low capacitance probe at the receiver inputs, i.e. after the interconnect's loading effects (backplane and/or cable) have occurred. A PRBS pattern or real system data pattern should be used to construct the eye pattern.

! Tip

When calculating ideal bit edge positions, do not round up/down to the nearest 10 picoseconds. Instead, calculate to the nearest picosecond.

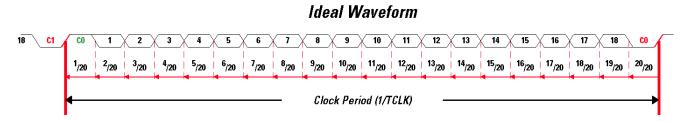
Important: Make calculations to the nearest picosecond.

2) Capture the entire eye pattern *at the receiver inputs* using a high bandwidth oscilloscope in variable persistence mode with a high speed (> 1 GHz), high impedance (> 100 k Ω) differential probe. The TCLK signal should be used as the trigger.

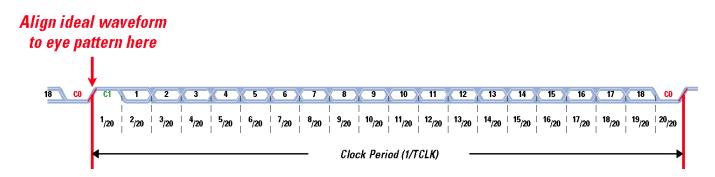


Full eye pattern captured by the scope set to variable persistence mode.

3) Use the vertical cursor function of the scope to place a vertical cursor over the average OV differential crossing point of the clock-0-bit/clock-1-bit low-to-high transition. This cursor position is now the ideal time point to which all other positions will be referenced.



Ideal bit edge positions are always multiples of T/20 away from the ideal clock0-clock1 low to high transition.



The receiver jitter margin for any bit on the eye pattern can be calculated based on its ideal bit edge positions.

Interconnect Jitter Budget (continued)

4) Select the bit "eye" pattern in which to place the receiver input jitter mask. The worst case bit, i.e. the bit with the most "closed" eye, is recommended. The ideal crossing points on either side of the n^{th} data bit will be $n^{*T/20}$ and $(n+1)^{*T/20}$ away from the ideal stop-start crossing point set in step 3, where T is period of the TCLK frequency. (18 data bits plus 2 clock bits = 20 bits.)

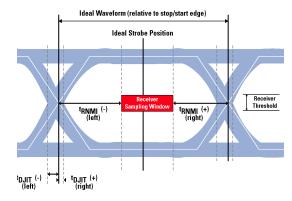
5) Calculate the ideal bit edges, being careful to avoid rounding errors, and place a cursor at both ideal bit edges of the selected bit.

6) Add $t_{RNMI-left}$ to the ideal left bit edge and $t_{RNMI-right}$ to the right ideal edge to get the positions of the receiver input jitter mask.

7) The height of the jitter mask is the receiver's differential input threshold V_{TH} - V_{TL}. This is typically \pm 50 mV, though the datasheet value of \pm 100 mV can be used if a more conservative estimate is desired.

8) The receiver input jitter mask should now look like a box inside the "eye" of

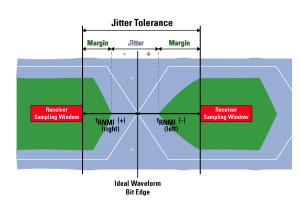
the bit. The "white area" (shown in green in the diagram at right) around the box is the relative noise margin of the link. As long as the captured eye opening stays out of this noise margin "box," the chipset should operate error-free.



Receiver input jitter eye mask construction.



Qualitative analysis of interconnect margin (green).



The t_{RNMI} specs can also be used around the ideal bit position to guage the percentage of jitter margin left before bit errors could occur.

Alternative Jitter Measurements

The $t_{RNMI-left/right}$ specs can also be used to get a quantitative estimate of remaining jitter margin. The quantity (t_{RNMI} - jitter)/ t_{RNMI} of the worst case side (see diagram at right) is the percentage jitter margin left before bit errors are expected to occur.

The total amount of jitter budget available for the interconnect (i.e. how much jitter budget is allowed for the cable or backplane) is calculated similarly by subtracting maximum transmitter deterministic jitter t_{DJIT} from receiver ideal noise margin t_{RNMI} :

Jitter budget left side: t_{RNMI-left} - t_{DJIT} (max)

Jitter budget right side: $t_{RNMI-right}$ + t_{DJIT} (min) $\ \{t_{DJIT} \ min \ is a negative number\}$



Troubleshooting

Troubleshooting

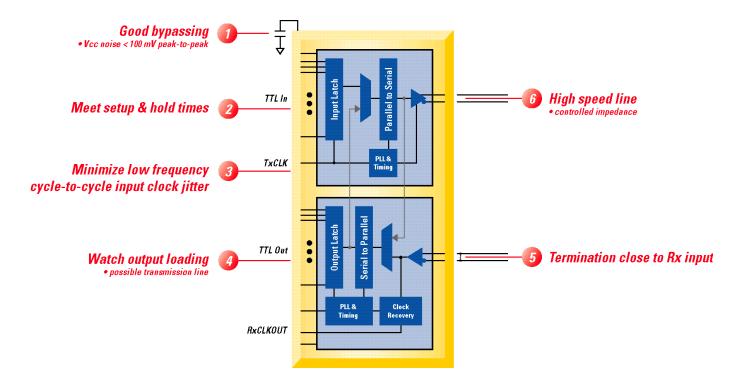
The DS92LV18 and SCAN921821 are robust, easy-to-use SerDes and application issues should be rare. If application problems do occur, the causes can normally be traced to a few simple, easy-to-check areas (listed in order of relevance):

■ Power Supply Noise: Excessive supply noise, especially on the PLL supply (PVDD), can add jitter to the transmitter serial output and affect the receiver data sampling. Keep supply noise under 100 mV peak-to-peak on the PVDD pins.

■ Transmit Clock: Minimize excessive cycle-to-cycle jitter on the transmit clock TCLK in the range or 200 kHz - 2 MHz which can add jitter to the transmitter serial output.

■ Serial Bus: Should follow LVDS PCB layout and backplane recommendations, using proper termination, avoiding long stubs, and assuring the termination resistor is close to the receiver input.

■ Parallel Bus: The parallel LVTTL signals should not violate any setup and hold times and should be free from excessive overshoot/undershoot.



Additional Technical Resources

National Semiconductor LVDS Feature Web Site

www.national.com/lvds is a one-stop-shop for device information and technical information such as application notes, white papers, the *LVDS Owner's Manual*, evaluation board documentation, IBIS models, frequently-askedquestions, online seminar materials, and much more.

LVDS Owner's Manual

The *LVDS Owner's Manual* teaches what LVDS is, how it works, what its advantages are, how to design with it. It should be part of every high speed interconnect designer's library. The *LVDS Owner's Manual* can be downloaded from the web at www.national.com/lvds or ordered from one of National's sales representatives.

RAPIDESIGNER® Slide Rule

National Semiconductor's *Transmission Line RAPIDESIGNER Slide Rule* makes PCB stripline and microstrip transmission line calculations quick and easy. The slide rule is available in both metric and English unit versions. Instructions and equations are given in application note AN-905.

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